

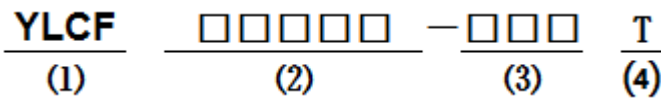
■ Features

- SMD construction, and low profile.
- High Impedance and Excellent Frequency Characteristic.
- Self Electromagnetic Shielding.
- Low Magnetic Flux Leakage.

■ Applications

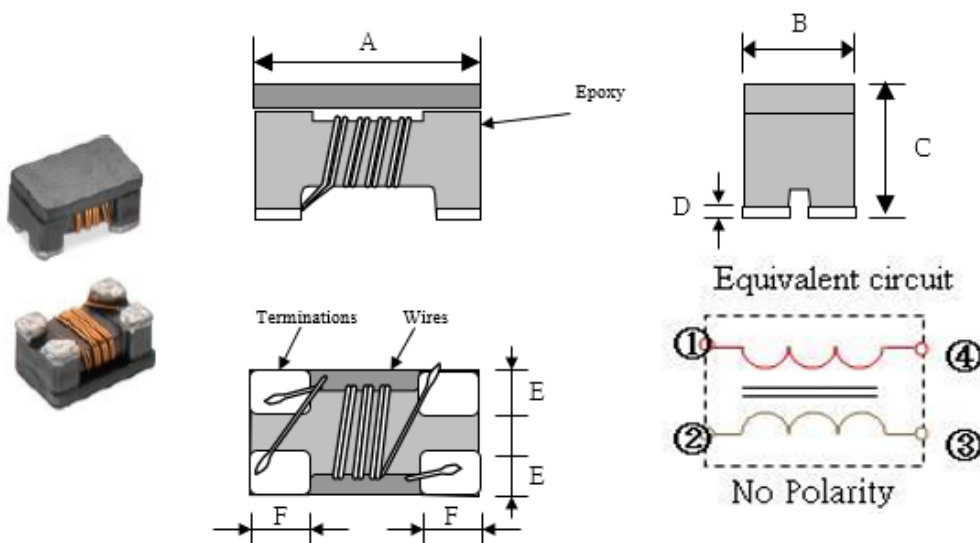
- LED Light, TV game, Monitor, etc.
- EMI common-mode noise.

■ Product Identification



- (1) : Type
- (2) : Dimensions
- (3) : Inductance Value(typ.)
- (4) : Taping

■ Shapes and Dimensions (Unit: mm)



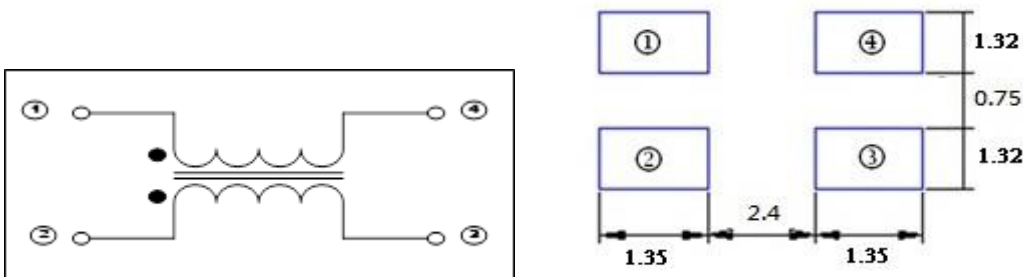
TYPE	A	B	C	D	E Typ.	F Typ.
YLCF4532A	4.5±0.2	3.2±0.2	2.8±0.2	0.2±0.1	1.2	1.0

■ YLCF4532A Series

Part Number	Z(Ω) Common mode Impedance (@10MHz)		L(μ H) Common Mode Inductance (@100KHz)	DCR (Ω) Max.	Idc(mA) Max.	Rated Voltage Vdc (V)Typical	Insulation Resistance IR (m Ω)Min.
	Min.	Typ.					
YLCF4532A-110T	Min.	300	(+50%/-30%)	0.60	250	50	10
	Typ.	700	11				
YLCF4532A-220T	Min.	500	(+50%/-30%)	1.00	200	50	10
	Typ.	1000	22				
YLCF4532A-510T	Min.	1000	(+50%/-30%)	1.00	200	50	10
	Typ.	2000	51				
YLCF4532A-101T	Min.	2000	(+50%/-30%)	2.00	150	50	10
	Typ.	5000	100				
YLCF4532A-201T	Min.	10000	(+50%/-30%)	4.50	100	50	10
	Typ.	15000	200				

1. Rated Current: Temp.rise 40°C Typ
2. Operating Temperature: -40°C up to +125°C
- 3.Storage Temperature: -20°C up to +40°C , 75% RH max.
4. If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk.

■ Equivalent Circuit & Recommended Footprint

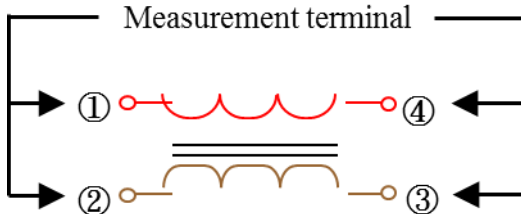


Test Equipment

Impedance / Inductance

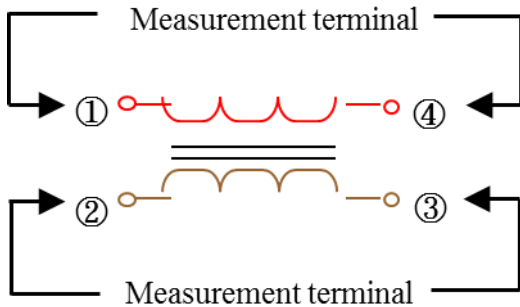
Measured by using Agilent 4291A RF Impedance Analyzer.

Measured by using Microtest 6377 LCR METER.



DC Resistance

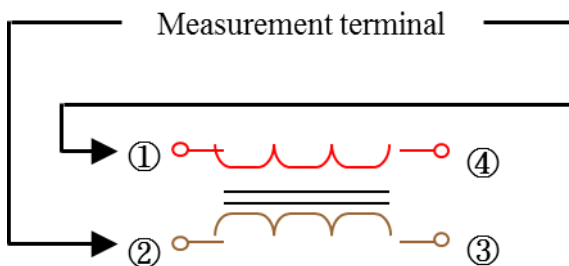
Measured by using Chroma 16502 mill ohm meter.



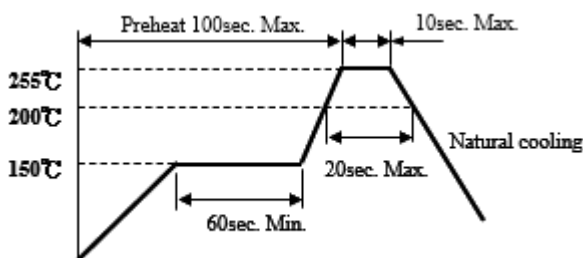
Insulation Resistance

Measured by using Chroma 19073

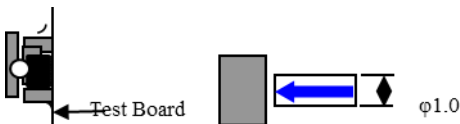
Measurement voltage : 50v ,Measurement time : 60 sec.



Recommended Soldering temp.graph



■ Reliability and Test Condition

Test item	Test condition / Test method	Specification										
Resistance to soldering heat	Solder: Sn99.5%-Cu0.5% Solder temperature: 260+5/-0℃。 Equipment: KUNG CHENG 5" 400℃、RF LCR METER。 Flux for lead free: Rosin. 9.5%。 Dip time: 10±0.5sec. Within: 1.5mm。 Magnification 10X。 Test the quantity: 30pcs。	Appearance : Cracking , chipping and any other defects harmful to the characteristics should not be allowed。 L: Within ±10% of initial value。										
Solder-ability Test	Preheat: 150℃,60sec.。 Solder: Sn99.5%-Cu0.5%。 Solder temperature: 245±5℃。 Equipment: KUNG CHENG 5" 400℃。 Flux for lead free: Rosin. 9.5%。 Dip time: 4±1sec. Within: 19~31mm。 Magnification 50X。 Test the quantity: 50pcs。	Appearance : More than 95% of the terminal electrode should be covered with solder。										
Terminal strength	Solder a chip to test substrate and then laterally apply a force in the arrow direction 	<table border="1" style="width: 100%; border-collapse: collapse; text-align: center;"> <thead> <tr> <th style="width: 60%;">Series No.</th> <th style="width: 40%;">F (Kg)</th> </tr> </thead> <tbody> <tr> <td>1210A/D</td> <td>0.2</td> </tr> <tr> <td>1608A/C</td> <td>0.5</td> </tr> <tr> <td>2012A/B/C</td> <td>0.5</td> </tr> <tr> <td>3216A</td> <td>1.0</td> </tr> </tbody> </table>	Series No.	F (Kg)	1210A/D	0.2	1608A/C	0.5	2012A/B/C	0.5	3216A	1.0
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1210A/D	0.2											
1608A/C	0.5											
2012A/B/C	0.5											
3216A	1.0											
Temperature Cycling Test	-40 +0/-2℃,+ 125 +2/-0℃ Kept for 30 minutes each,1000 cycles, Transfer Time: 5 minutes Equipment: TH-1S-C、RF LCR METER Test the quantity: 90pcs。	Appearance: Cracking, chipping and any other defects harmful to the characteristics should not be allowed。 L: Within ±10% of initial value。										
Humidity Resistance Test	85~90% R.H.*25~65 +2/-0℃ *10 Cycles Equipment: TH-1S-C、RF LCR METER Test the quantity: 90pcs。 Rated Current 100%	Appearance: Cracking, chipping and any other defects harmful to the characteristics should not be allowed。 L: Within ±10% of initial value。										

■ Reliability and Test Condition

Test item	Test condition / Test method	Specification
Thermal Shock Test	CONDITION(Air-to-air): -40 +0/-2℃,+ 125 +2/-0℃ Kept for 15 minutes each,300 cycles, Transfer Time: 20 seconds Equipment: TH-1S-C、 RF LCR METER Test the quantity: 90pcs。	Appearance: Cracking, chipping and any other defects harmful to the characteristics should not be allowed。 L: Within ±10% of initial value。
High Temperature Exposure	125 +0/-2℃ *1000±12HRs Equipment: TH-1S-C、 RF LCR METER Test the quantity: 90pcs。	Appearance: Cracking, chipping and any other defects harmful to the characteristics should not be allowed。 L: Within ±10% of initial value。
Biased Humidity Test	85% R.H.*85 +2/-0℃ *1000±12HRs Equipment: TH-1S-C、 RF LCR METER Test the quantity: 90pcs。	Appearance: Cracking, chipping and any other defects harmful to the characteristics should not be allowed。 L: Within ±10% of initial value。
Vibration Test	It shall be soldered on substrate。 Oscillation Frequency: 10~2K ~10Hz for 20 minute。 Equipment: Vibration checker。 Total Amplitude: 1.52mm±10%。 Testing Time : 12 hours(20 minutes , 12 cycles each of 3 orientations) Test the quantity: 30pcs。	Appearance: Cracking, chipping and any other defects harmful to the characteristics should not be allowed。 L: Within ±10% of initial value。

Application Notice

·Storage Conditions

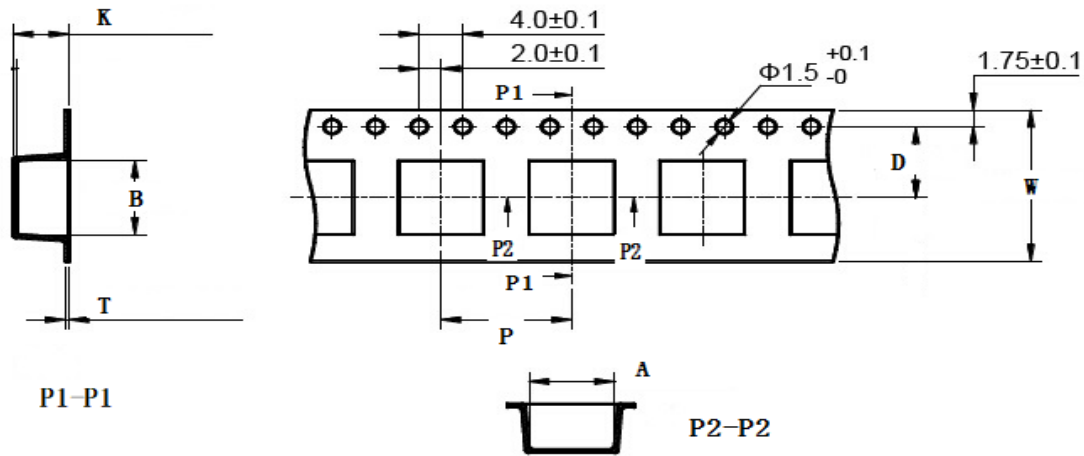
To maintain the solderability of terminal electrodes:

1. products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40℃ and 60% RH.
3. Recommended products should be used within 6 months form the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

·Transportation

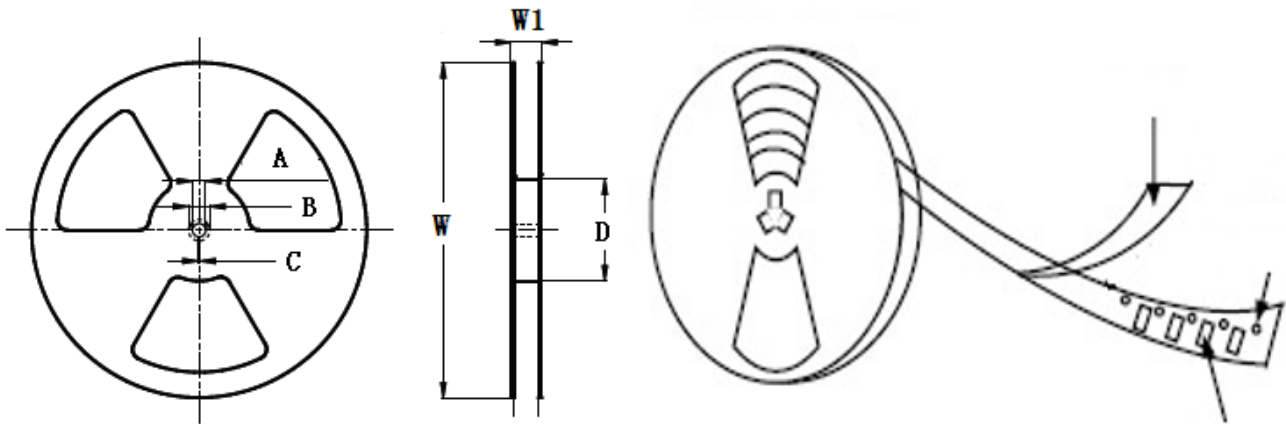
1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

Taping Dimensions(Unit:mm)



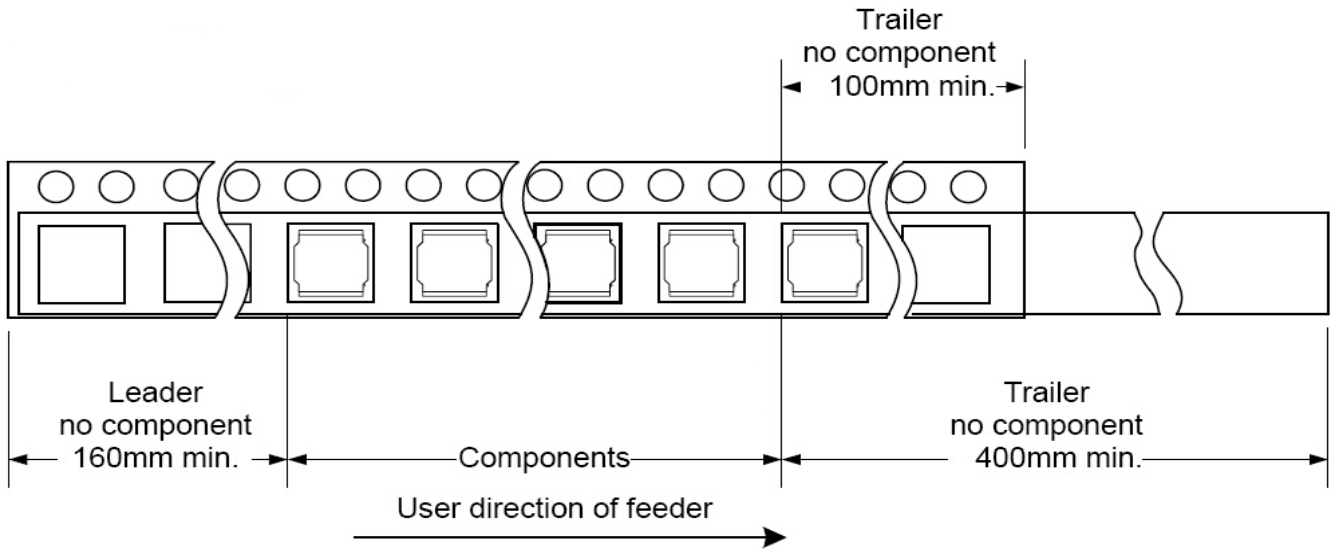
TYPE	W	A	B	D	P	K Max	T Max	MPQ
YLCF4532A	12.00	3.45	4.90	5.50	8.00	3.05	0.25	500

Reel Dimensions(Unit:mm)

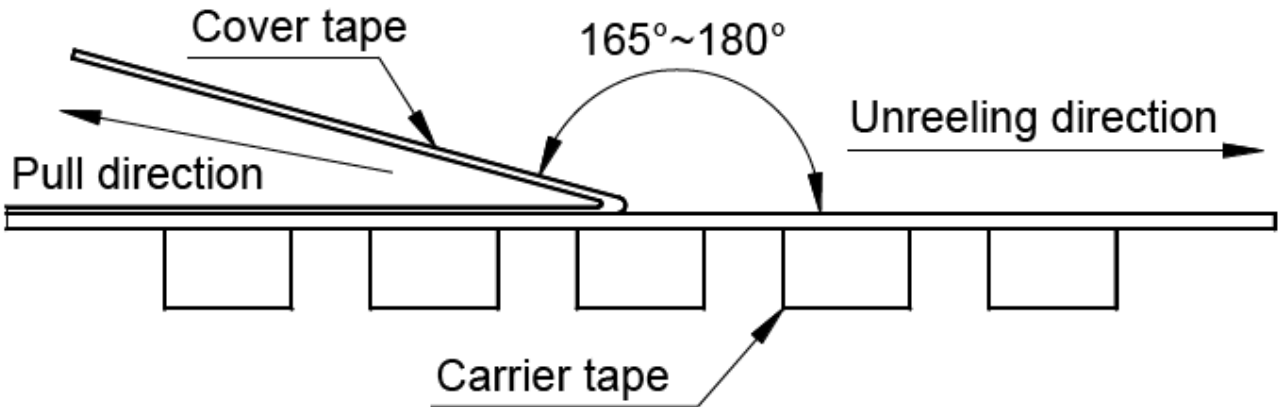


TYPE	W	W1	A	B	C	D
YLCF4532A	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

Direction of rolling



Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.